

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L7	8	(discrete adj component) near5 substrate near5 chip	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2002/05/22 14:15
2	BRS	L8	1220	conductor near5 substrate and (wir\$5 adj bonding)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2002/05/22 14:17
3	BRS	L9	123	conductor near5 substrate and (wir\$5 adj bonding)and stack	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2002/05/22 16:50
4	BRS	L10	0	(conductive adj adheside) and chip	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2002/05/22 16:51
5	BRS	L11	0	conductive adj adheside	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2002/05/22 16:51

	Comments	Error Definition	Errors
1			0
2			0
3			0
4			0
5			0

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L12	4071	(conductive adj adhesive) and chip	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2002/05/22 16:52
7	BRS	L13	1215	(conductive adj adhesive) and chip and wiring	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2002/05/22 16:54

	Comments	Error Definition	Errors
6			0
7			0